

## S3X-70M



- Quick wetting through components with large thermal mass such as connectors
- Remarkable wetting performance to nickel and brass leads
- Realizes low flux spitting and bridging in slide-soldering
- No REACH restricted SVHC substances contained

### ◆ Wetting performance

#### Test method

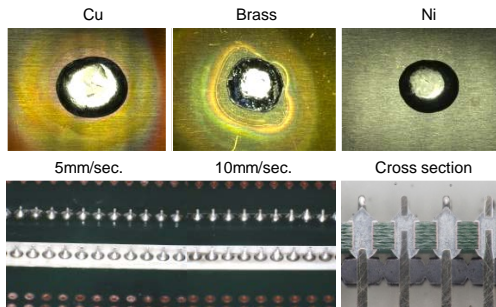
Heat a SAC305 alloy ring with solid flux added on the solder bath at 300°C for 5 sec.

Solder spreads quickly even on Brass and Nickel.

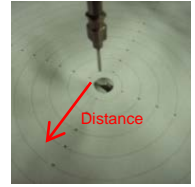
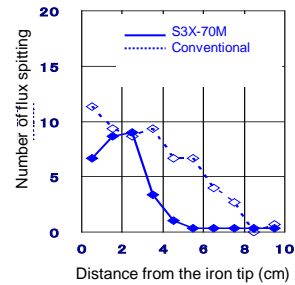
#### Test method

Conduct a drag soldering to 21 pins at one time (Iron tip temp. = 370°C)

No bridges are seen maximum at 10mm/sec.



### ◆ Low flux spitting



Iron tip temp.: 380°C

### ◆ Product specifications

Product	S3X-70M
Alloy composition (%)	Sn 3.0Ag 0.5Cu
Melting point (°C)	217-219
Flux content (%)	3.0
Halide content (%)	0.09
Diameter of wire (mm)	0.3, 0.4, 0.5, 0.6, 0.8, 1.0, 1.2, 1.6

\*Specifications are subject to change.

### ◆ Hand soldering products line-up

#### ■ Flux cored solder wire

S01X7Ca-70M	Anti-erosion low Ag alloy (Sn0.1Ag0.7CuCo+α)
S03X7Ca-70M	Anti-erosion low Ag alloy (Sn0.1Ag0.7CuCo+α)
SB6N-70M	High reliability, crack free alloy

#### ■ Tacky flux

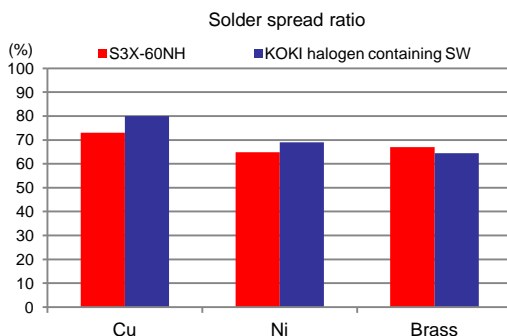
TF-M880R	For repairing BGA/CSP, halogen free
TF-MP1	For PoP soldering

# Halogen free type solder wire

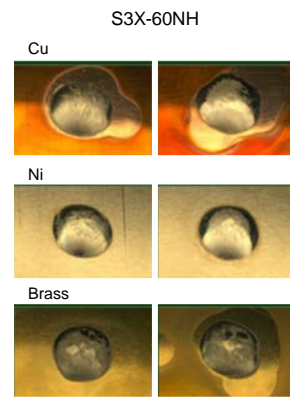
## S3X-60NH

- Halogen free (Cl, Br  $\leq$  900ppm / Cl + Br  $\leq$  1500ppm)
- Secures equivalent wetting performance to conventional halogen containing product

### ◆ Wetting performance



S3X-60NH secures almost equivalent or even better wetting performance to KOKI halogen containing solder wire with Cu, Ni and Brass.



### ◆ Product specifications

Product	S3X-60NH
Alloy composition (%)	Sn 3.0Ag 0.5Cu
Melting point (°C)	217 - 219
Flux content (%)	3.0
Halide content (%)	0.0
Diameter of wire (mm)	0.3, 0.4, 0.5, 0.6, 0.8, 1.0, 1.2, 1.6

\*Specifications are subject to change.